



## Material Content Data Sheet



<b>Sales Product Name</b>		SAK-XC164CM-16F40F BA		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000789442						
<b>Package</b>		PG-LQFP-64-4		<b>Weight*</b>		379.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	19.143	5.04	5.04	50427	50427
leadframe	non noble metal	magnesium	7439-95-4	0.179	0.05		471	
	inorganic material	silicon	7440-21-3	0.775	0.20		2042	
	non noble metal	nickel	7440-02-0	3.578	0.94		9426	
wire	non noble metal	copper	7440-50-8	114.739	30.23	31.42	302252	314191
	noble metal	gold	7440-57-5	1.871	0.49	0.49	4929	4929
	encapsulation	organic material	carbon black	1333-86-4	1.150	0.30		3030
encapsulation	plastics	epoxy resin	-	31.052	8.18		81800	
	inorganic material	silicondioxide	60676-86-0	197.814	52.13	60.61	521095	605925
leadfinish	non noble metal	tin	7440-31-5	4.118	1.08	1.08	10847	10847
plating	noble metal	silver	7440-22-4	1.710	0.45	0.45	4506	4506
glue	plastics	epoxy resin	-	0.697	0.18		1835	
	noble metal	silver	7440-22-4	2.786	0.73	0.91	7340	9175
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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